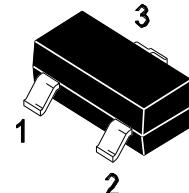
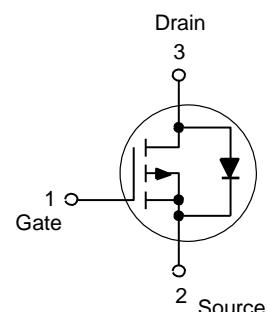


**PJM2301PSA-S****P- Enhancement Mode Field Effect Transistor****Features**

- $V_{DS} = -20V$ $I_D = -2A$
- $R_{DS(ON)} = 120m\Omega$ (typ) @ $V_{GS} = -2.5V$
 $R_{DS(ON)} = 88m\Omega$ (typ) @ $V_{GS} = -4.5V$
- High power and current handing capability
- Halogen and Antimony Free
- Surface mount package

SOT-23

1. Gate 2. Source 3. Drain
Marking : S01**Applications**

- Battery protection
- Load switch
- Power management

Absolute Maximum Ratings $T_C = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	- 20	V
Gate-Source Voltage	V_{GS}	± 12	
Continuous Drain Current	I_D	-2	A
Pulsed Drain Current <small>Note1</small>	I_{DM}	- 10	
Maximum Power Dissipation	P_D	0.7	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	- 55 to 150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient <small>Note2</small>	$R_{\theta JA}$	178	$^\circ C/W$



PJM2301PSA-S

P- Enhancement Mode Field Effect Transistor

Electrical Characteristics

T_C=25°C unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Parameters						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = - 250 μA	- 20			V
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 12V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 20 V, V _{GS} = 0 V			- 1	μA
Gate-Source Threshold Voltage ^{Note3}	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 0.4		- 1	V
Drain-Source On-State Resistance ^{Note3}	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 2 A		88	120	mΩ
		V _{GS} = - 2.5 V, I _D = - 1 A		120	180	
Dynamic Parameters						
Forward Transconductance ^{Note3}	g _{fs}	V _{DS} = - 5 V, I _D = - 2 A	4			S
Input Capacitance	C _{iss}	V _{DS} = - 10 V, V _{GS} = 0 V, f = 1 MHz		405		pF
Output Capacitance	C _{oss}			75		
Reverse Transfer Capacitance	C _{rss}			55		
Switching Parameters						
Total Gate Charge	Q _g	V _{DS} = - 10 V, V _{GS} = - 4.5 V, I _D = - 2 A		2.9		nC
Gate-Source Charge	Q _{gs}			0.45		
Gate-Drain Charge	Q _{gd}			0.75		
Turn-On Delay Time	t _{d(on)}	V _{DD} = - 10 V, R _L = 10 Ω I _D = - 1 A, V _{GEN} = - 4.5 V, R _G = 1 Ω		11	20	ns
Rise Time	t _r			35	60	
Turn-Off Delay Time	t _{d(off)}			30	50	
Fall Time	t _f			10	20	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current ^{Note2}	I _S				- 2	A
Body Diode Voltage ^{Note3}	V _{SD}	I _S = - 2 A			- 1.2	V

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. Surface Mounted on FR4 Board, t ≤ 10 sec.

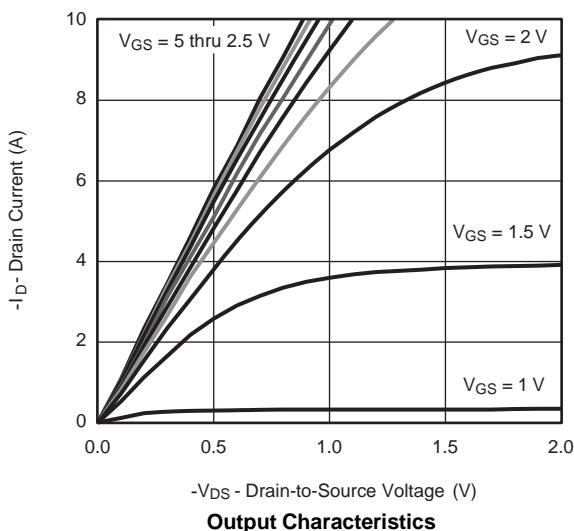
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.



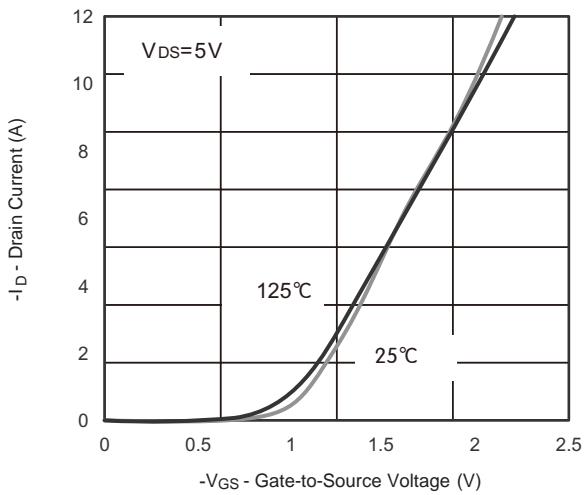
PJM2301PSA-S

P- Enhancement Mode Field Effect Transistor

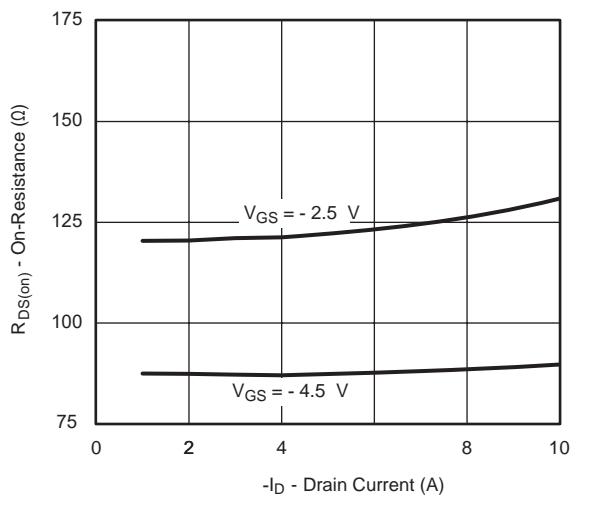
Typical Characteristics Curves



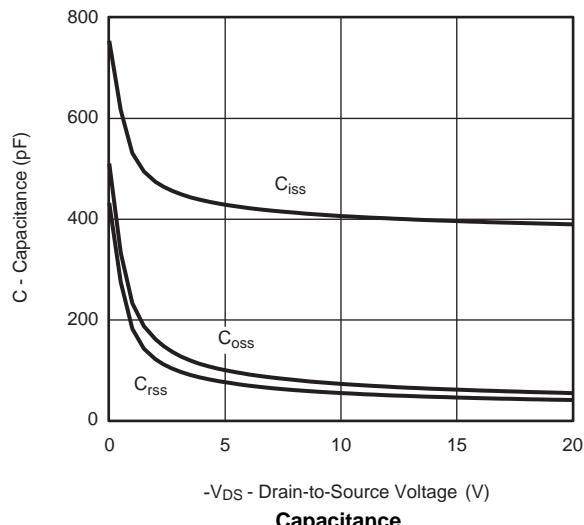
Output Characteristics



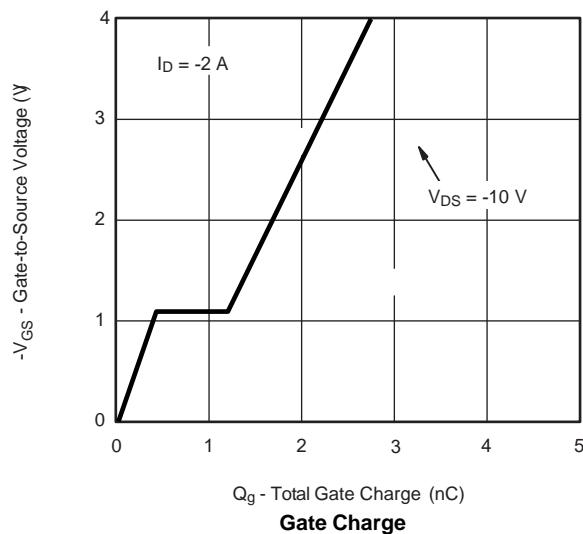
Transfer Characteristics



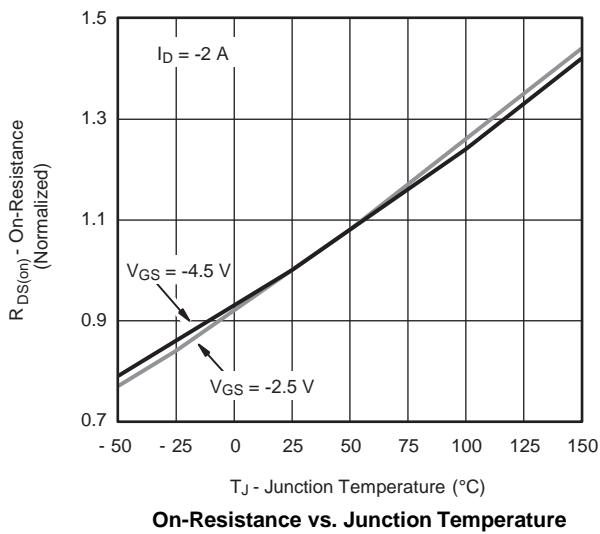
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



Gate Charge

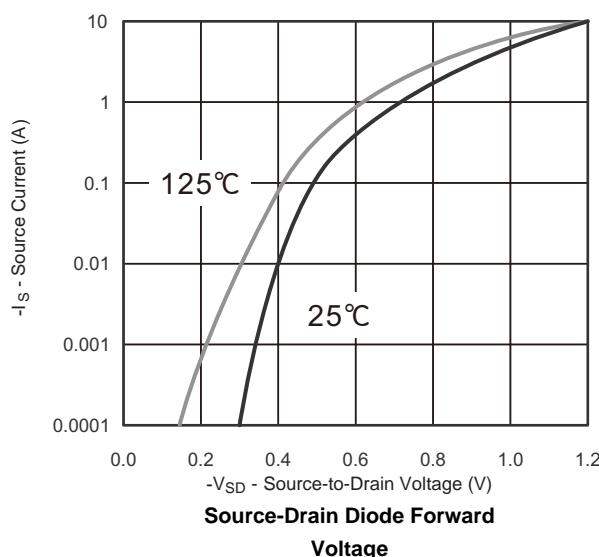


On-Resistance vs. Junction Temperature

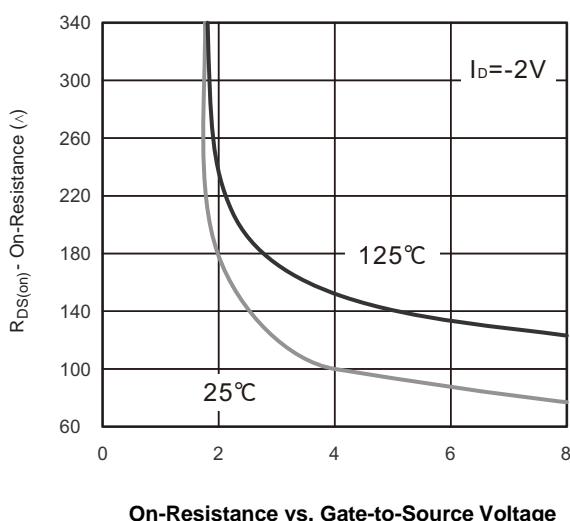


PJM2301PSA-S

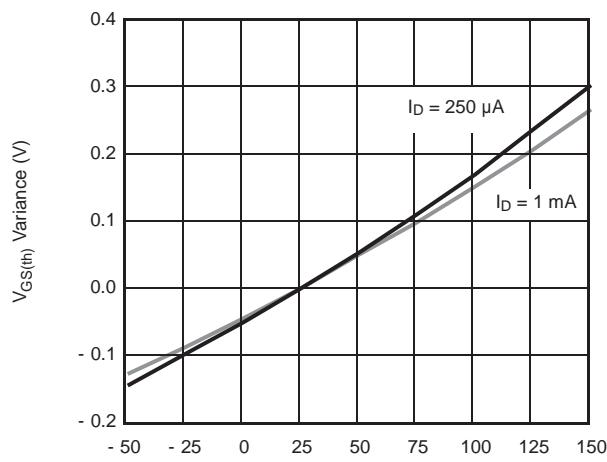
P- Enhancement Mode Field Effect Transistor



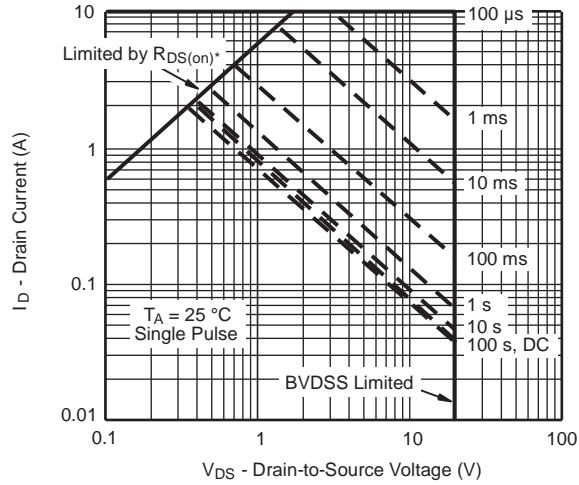
Source-Drain Diode Forward Voltage



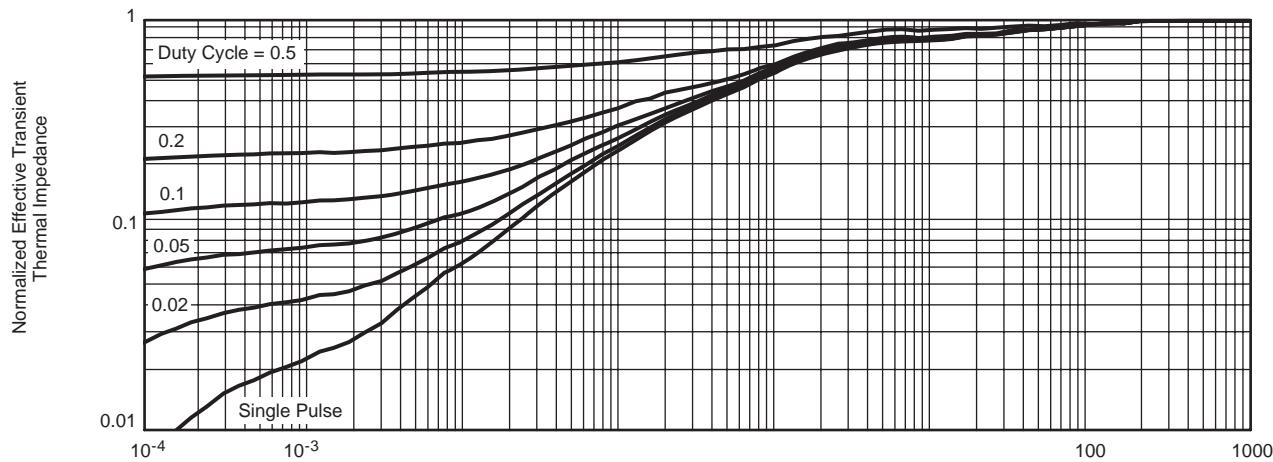
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Safe Operating Area

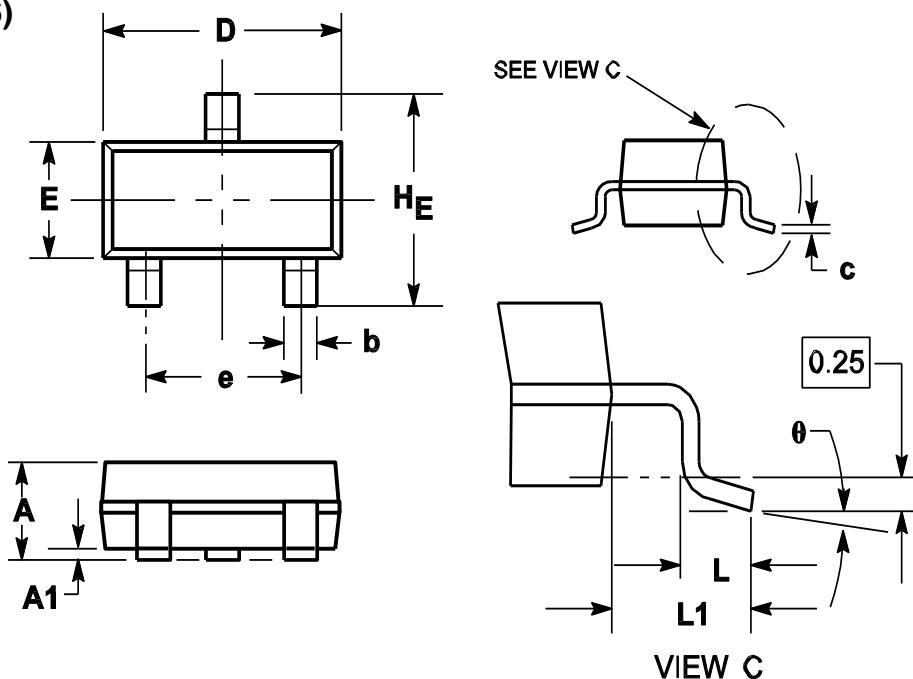


Normalized Thermal Transient Impedance, Junction-to-Ambient

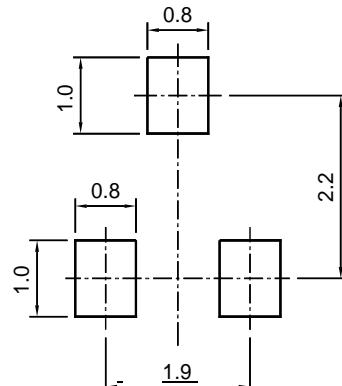


Package Outline

SOT-23 (TO-236)



Symbol	Dimensions in millimeter		
	Min.	Typ.	Max.
A	0.900	1.025	1.150
A1	0.000	0.050	0.100
b	0.300	0.400	0.500
c	0.080	0.115	0.150
D	2.800	2.900	3.000
E	1.200	1.300	1.400
HE	2.250	2.400	2.550
e	1.800	1.900	2.000
L1	0.550REF		
L	0.300		0.500
θ	0°		8°



SOT-23 (TO-236)
Recommended soldering pad

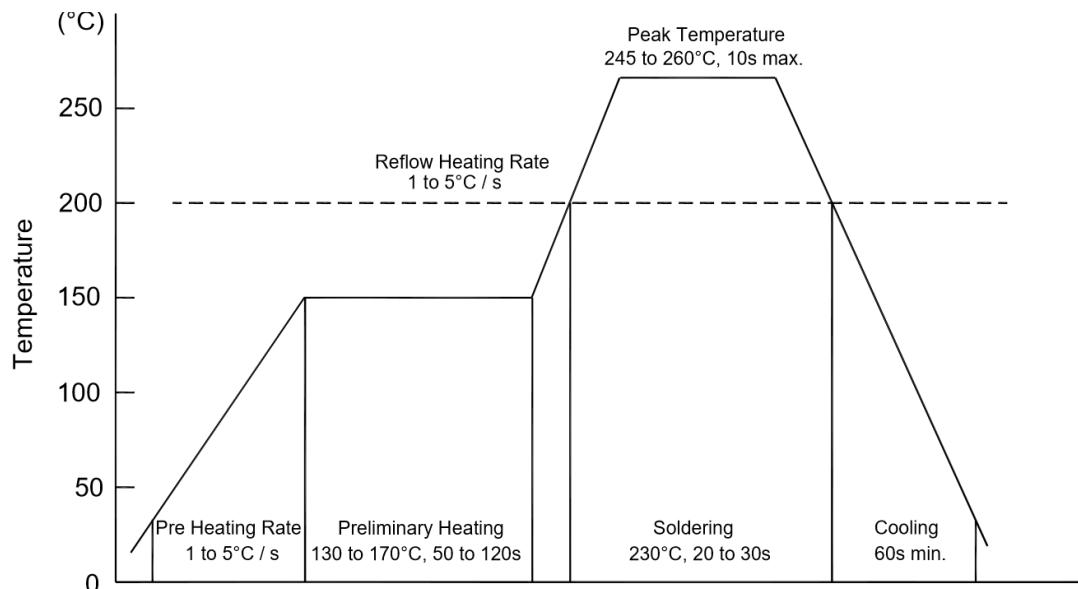
Ordering Information

Device	Package	Shipping
PJM2301PSA-S	SOT-23	3000/Reel&Tape(7inch)



Conditions of Soldering And Storage

◆ Recommended condition of reflow soldering



Recommended peak temperature is over 245 °C. If peak temperature is below 245 °C, you may adjust the following parameters:

- Time length of peak temperature (longer)
- Time length of soldering (longer)
- Thickness of solder paste (thicker)

◆ Conditions of hand soldering

- Temperature: 370 °C
- Time: 3s max.
- Times: one time

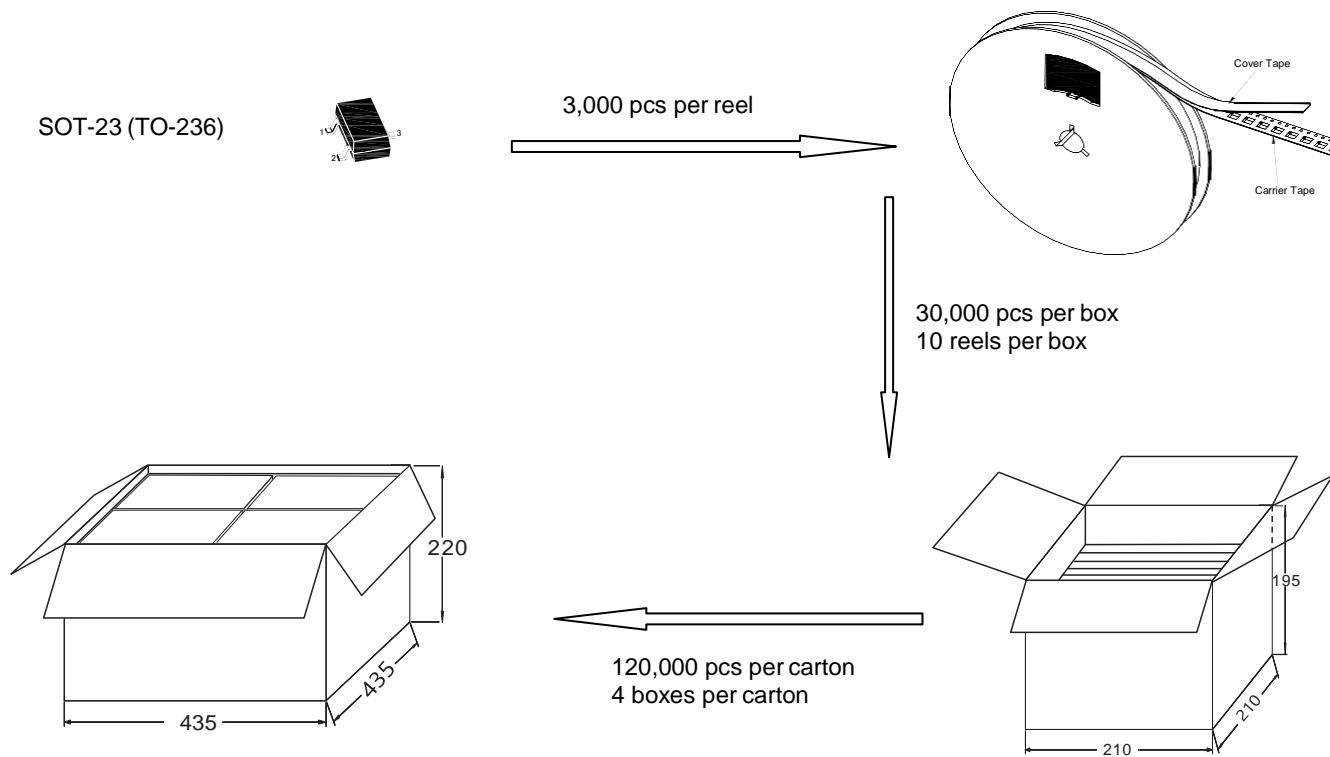
◆ Storage conditions

- **Temperature**
5 to 40 °C
- **Humidity**
30 to 80% RH
- **Recommended period**
One year after manufacturing



Package Specifications

◆ The method of packaging



◆ Embossed tape and reel data

